Special Issue

Thermal Management of Electronic Packaging

Message from the Guest Editors

This Special Issue focuses on innovative solutions, novel contributions, critical reviews, case studies, or theoretical models of Thermal Management of Electronic Packaging studies from microchip-level to room-level (including data center cooling solutions). The invited topics include, but are not limited to:

- thermodynamic (energy and exergy) analysis;
- heat transfer enhancement; system design and optimization;
- thermo- and/or techno-economic assessments of the air-cooled and liquid-cooled solutions;
- thermal energy store via sensible or latent heat mechanisms.

Guest Editors

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Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Editor-in-Chief

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